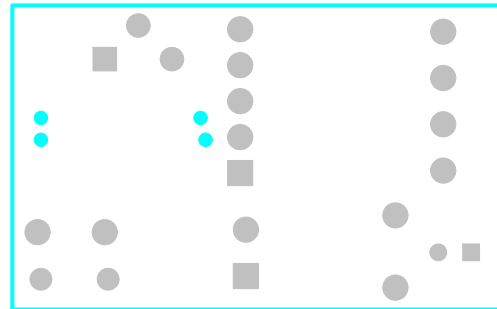
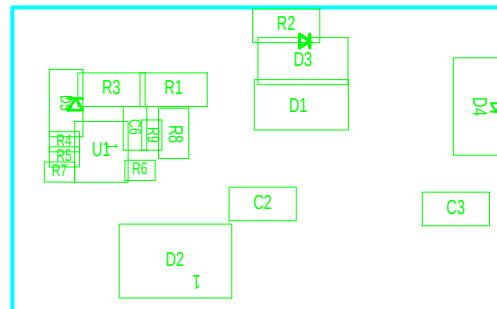


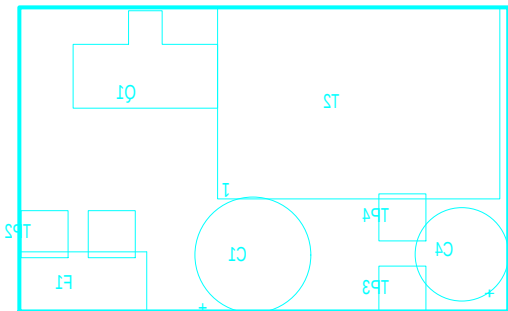
| TEXAS INSTRUMENTS | | Copper | | Silkscreen | | S Mask | Assembly | | Fab Drawing |
|-----------------------------|-------------------------------|---------------------|----------------------|------------------------------|-----|--------|-----------------------|-----|-------------|
| | | Top Side | Bot | Top | Bot | Top | Top | Bot | |
| Board No. PMP8764 | Rev. A | L1 | | | | | | | |
| Date: 11-27-2012 | Filename: PMP8764_REVA.PCB | Engineer: B King | PCB Dsgnr: B King | Modified Date: 11-27-2012 | | | Software PADs v9.3 | | |



| TEXAS INSTRUMENTS | | Copper | | Silkscreen | | S Mask | Assembly | | Fab Drawing |
|-----------------------------|-------------------------------|---------------------|----------------------|------------------------------|-----------------------|--------|----------|--|-------------|
| | | Top Side | Top | Bot | Top | Top | Bot | | |
| Board No. PMP8764 | Rev. A | | | | | | | | |
| Date: 11-27-2012 | Filename: PMP8764_REVA.PCB | Engineer: B King | PCB Dsgnr: B King | Modified Date: 11-27-2012 | Software PADs v9.3 | | | | |



| | | | | | | | | | | | |
|-------------------|----------------------------|------------------|--|-------------------|-----|---------------------------|--|----------|-----|--------------------|--|
| TEXAS INSTRUMENTS | | Copper | | Silkscreen | | S Mask | | Assembly | | Fab Drawing | |
| | | Top Side | | Top | Bot | Top | | Top | Bot | | |
| Board No. PMP8764 | | Rev. A | | L1 | | | | TA | | | |
| Date: 11-27-2012 | Filename: PMP8764_REVA.PCB | Engineer: B King | | PCB Dsgnr: B King | | Modified Date: 11-27-2012 | | | | Software PADs v9.3 | |

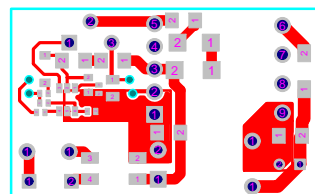


| TEXAS INSTRUMENTS | | Copper | | Silkscreen | | S Mask | Assembly | | Fab Drawing |
|-------------------|----------------|-----------|------------------|------------|--------|------------|----------|----------------|-----------------------|
| | | Top Side | Top | Bot | Top | Top | Bot | | |
| Board No. | PMP8764 | Rev. | A | | | | | BA | |
| Date: | 11-27-2012 | Filename: | PMP8764_REVA.PCB | Engineer: | B King | PCB Dsgnr: | B King | Modified Date: | 11-27-2012 |
| | | | | | | | | | Software PADs v9.3 |

| FABRICATION CHART | | | |
|---|---|--|---|
| FINISHED THICKNESS | SILKSCREEN | SOLDERMASK | FINISHED COPPER WEIGHT |
| <input type="checkbox"/> 0.031 <input checked="" type="checkbox"/> 0.062 <input type="checkbox"/> 0.093 <input type="checkbox"/> 0.125 | <input checked="" type="checkbox"/> LAYER 1 <input checked="" type="checkbox"/> LAYER 2 <input type="checkbox"/> NONE | <input checked="" type="checkbox"/> LAYER 1 <input type="checkbox"/> LAYER 2 <input type="checkbox"/> NONE | <input type="checkbox"/> 1 OZ. <input checked="" type="checkbox"/> 2 OZ. <input type="checkbox"/> OTHER _____ |
| DESIGN | TRACE/GAP SPACING | LAYER COUNT | |
| <input type="checkbox"/> SMD <input type="checkbox"/> THRU-HOLE <input checked="" type="checkbox"/> MIX | <input checked="" type="checkbox"/> 0.010/0.010 <input type="checkbox"/> 0.008/0.007 <input type="checkbox"/> 0.006/0.006 | <input checked="" type="checkbox"/> SINGLE SIDED <input type="checkbox"/> 2 LAYER <input type="checkbox"/> 4 LAYER <input type="checkbox"/> OTHER _____ | |

NOTES: UNLESS OTHERWISE SPECIFIED

- MATERIAL:** ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE, BONDING MATERIALS AND SOLDERMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET UL-796 REQUIREMENTS AND BE RoHS COMPLIANT AND HAVE A FLAMMABILITY OF UL94V-0.
- BASE LAMINATE:** PLASTIC SHEET, LAMINATED METAL CLAD, BASE MATERIAL NEMA TYPE FR-4 OR EQUIVALENT, W/Tg = 180 Deg C OR HIGHER. MINIMUM DECOMPOSITION TEMP (Td) OF 340 Deg C. GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH FAB CHART OR STACKUP DETAIL, COMPLIANT WITH LEAD FREE PROCESS.
- SOLDERMASK:** SOLDERMASK OVER BARE COPPER (SMOBC) USING LIQUID PHOTO-IMAGEABLE SOLDERMASK IN ACCORDANCE WITH IPC-SM-840. COLOR: GREEN. MINOR SOLDERMASK ADJUSTMENTS TO FACILITATE PCB FAB OR ASSEMBLY ARE ALLOWED PROVIDED NO DEFECTS ARE CREATED AS A RESULT.
- PLATING:** NO PLATING IN HOLES REQUIRED.
- FINISH:** PLATE WITH RoHS COMPLIANT, IMMERSION SILVER PREFERRED, IMMERSION GOLD or TIN OR Sn/Ag/Cu, WITH RMA FLUX, 0.0005" +/- 0.0003" THICK MIN ALL EXPOSED AREAS AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.
- LEGEND:** IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK.
- MARKINGS:** BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK). LOCATION OPTIONAL.
- WORKMANSHIP:** BOARD IS TO BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER.
- DOCUMENTATION:** PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.
- DRILL SIZES:** HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.
- TOLERANCES:** UNLESS OTHERWISE SPECIFIED PCB TOLERANCES SHALL BE:
PCB THICKNESS TOLERANCE = +/- 10% RELATIVE TO FINISHED THICKNESS, MEASURED FROM COPPER TO COPPER.
PCB DIMENSIONAL TOLERANCE = +/- .005 INCHES RELATIVE TO BOARD PROFILE AND DRILL TO EDGE DIMENSIONS.
FINISHED HOLE DIAMETERS SHALL BE +/- .003 INCHES RELATIVE THE DRILL TABLE DIMENSIONS.
- PANEL BORDER:** ANY METAL IN BORDER AREA INCLUDING PART NUMBER, DATECODE AND/OR REVISION LETTERS MUST BE COVERED WITH SOLDERMASK.
- PROCESS CHANGES:** NO DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION FROM TEXAS INSTRUMENTS.



| TEXAS INSTRUMENTS | | Copper | | Silkscreen | | S Mask | Assembly | | Fab Drawing | | |
|-------------------|------------|-----------|------------------|------------|--------|-------------|----------|----------------|-------------|-----------|-----------|
| | | Top Side | Bot | Top | Bot | Top | Top | Bot | | | |
| Board No. | PMP8764 | Rev. | A | L1 | | | | | FB | | |
| Date: | 11-27-2012 | Filename: | PMP8764_REVA.PCB | Engineer: | B King | PCB Design: | B King | Modified Date: | 11-27-2012 | Software: | PADS v9.3 |

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